Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	(("6833609") or ("6580159")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 12:11
S2	11009	@ad<="20040329" and (257/668). ccls. or (257/676).ccls. or (257/737).ccls. or (257/784).ccls. or (257/787).ccls. or (257/E23.065). ccls. or (257/E23.125).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:04
S3	44	@ad<="20040329" and 'tape substrate' and 'chip' and 'inductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:08
S5	79	@ad<="20040329" and 'tape' and 'chip' and 'balun'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:40
S6	64	@ad<="20040329" and 'tape' and 'chip' and 'balun' and 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:06
S7	15	@ad<="20040329" and 'tape' and 'chip' and 'coupler' and 'balun' and 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:45
S8	9	@ad<="20040329" and 'tape' and 'chip' and 'coupler' and 'balun' and 'filter' and 'inductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/09/19 09:32
S9	18	@ad<="20040329" and 'tape' with 'package' and 'chip' and 'coupler' and 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/12/26 08:12
S10	5	@ad<="20040329" and 'tape substrate' and 'chip' and 'transmission line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:53
S11	101	@ad<="20040329" and 'package' and 'tape' and 'IC' with 'inductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:32

S12	24	@ad<="20040329" and 'package' and 'tape' and 'IC' with 'coupler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:07
S13	117	@ad<="20040329" and 'package' and 'tape' and 'IC' with 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:07
S14	36	@ad<="20040329" and 'RF' and 'package' and 'tape' and 'IC' with 'inductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:44
S15	1	"6310386".PN.	USPAT; USOCR	OR	ON	2005/05/31 13:24
S16	1	"6005466".PN.	USPAT; USOCR	OR	ON	2005/05/31 13:24
S17		@ad<="20040329" and 'RF' and 'tape' and ('IC' or 'chip') same 'inductor' same 'coupler' same 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/05/31 13:28
S18	3	@ad<="20040329" and 'RF' and 'tape' and ('IC' or 'chip') same 'inductor' same 'coupler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:28
S19	5	@ad<="20040329" and 'tape carrier' and 'IC' same 'inductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:35
S20	54	@ad<="20040329" and 'semiconductor package' and 'radio frequency' and 'transmission' with 'element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:50
S21	367	@ad<="20040329" and 'tape' and 'package' and ('radio frequency' or 'RF') and 'transmission' with 'element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:51
S22	266	@ad<="20040329" and 'tape' and 'package' and ('radio frequency' or 'RF') and 'transmission' with 'element' and ('IC' or 'chip')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:52
S23	32	@ad<="20040329" and 'tape' and 'package' and ('radio frequency' or 'RF') with 'modules' and 'transmission' with 'element' and ('IC' or 'chip')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 13:52

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S24	1	"6218729".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:24
S25	1	"6169329".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:25
S26	1	"6180445".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:25
S27	2	crowley-sean.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2005/05/31 14:33
S28	5	davis-terry.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:34
S29	. 5	bancod-ludovico.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:35
S30	1	darveaux-robert.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 14:35
S31	1	"20020140068".PN.	US-PGPUB	OR	ON	2005/05/31 14:42
S32	1	"20020140061".PN.	US-PGPUB	OR	ON	2005/05/31 14:42
S33	1	"20020024122".PN.	US-PGPUB	OR	ON	2005/05/31 14:42
S34	1	"20020011654".PN.	US-PGPUB	OR	ON	2005/05/31 14:42
S35	1	"20010008305".PN.	US-PGPUB	OR	ON	2005/05/31 14:42
S36	· 1	"6507120".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:42
S37	1	"6218729".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:49
S38	1	"6310386".PN	USPAT; USOCR	OR	ON	2005/05/31 14:57
S39	1	"6005466".PN	USPAT; USOCR	OR	ON	2005/05/31 14:57
S40	1	"5939783".PN.	USPAT; USOCR	OR	ON	2005/05/31 14:58
S41	52	@ad<="20040329" and 'TAB' and 'chip' and 'inductor' and 'via' and 'encapsulation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:24
S42	1	"6444499".PN.	USPAT; USOCR	OR	ON	2005/05/31 15:11
S43	1	"6184463".PN.	USPAT; USOCR	OR	ON	2005/05/31 15:11

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S46	74	@ad<="20040329" and 'polyimide' with 'substrate' same 'via' and 'chip' and 'transmission line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:42
S47	14	@ad<="20040329" and 'polyimide' with 'substrate' same 'via' and 'chip' same 'transmission' with 'element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:26
S48	96	@ad<="20040329" and 'polyimide' same 'via' and 'chip' and 'transmission' with 'element'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 15:55
S49	1	"6410858".PN.	USPAT; USOCR	OR	ON	2005/05/31 15:47
S50	1	"6407929".PN.	USPAT; USOCR	OR	ON	2005/05/31 15:47
S51	60	@ad<="20040329" and 'polyimide' same 'via' and 'chip' and 'transmission' with 'element' and 'resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:03
S52	102	@ad<="20040329" and 'high' with 'frequency' with 'module' and 'encapsulation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:06
S53	. 30	@ad<="20040329" and 'high' with 'frequency' with 'module' and 'passive' and 'encapsulation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:40
S54		@ad<="20040329" and 'high' with 'frequency' with 'module' and 'passive' same 'inductor' with 'balun'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:40
S55	49	@ad<="20040329" and 'high' with 'frequency' with 'module' and 'passive' same 'inductor' with 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:41
S56	4	@ad<="20040329" and 'high' with 'frequency' with 'module' and 'passive' same 'inductor' with 'filter' with 'coupler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 16:41
S57	1221	@ad<="20040329" and (257/734). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19

S58	180	@ad<="20040329" and (257/748). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:18
S59	2335	@ad<="20040329" and (361/760-763).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 13:39
S60	4	@ad<="20040329" and 'tape substrate' and 'chip' and 'transmission line' and 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 08:33
S61	222	@ad<="20040329" and 'tape substrate' and 'chip' and 'via' and 'terminal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/09/25 08:36
S62	1	@ad<="20040329" and 'tape substrate' and 'chip' and 'via' and ('balun' or 'shortwave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 08:37
S63	1	@ad<="20040329" and 'tape substrate' and 'chip' and ('balun' or 'shortwave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 08:37
S64	281	@ad<="20040329" and 'tape' and 'chip' and ('balun' or 'short wave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 09:04
S65	1	"6410858".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:40
S66	1	"6407929".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:40
S67	1	"6388207".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:40
S68	1	"6370013".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:41
S69	1	"6353540".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:41
S70	. 1	"6319542".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:41
S71	1	"6252761".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:42
S72	1	"6153290".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:42

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S73	1	"6153290".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:42
S74	1	"6021050".PN.	USPAT; USOCR ·	OR	ON	2005/09/25 08:42
S75	1	"6021050".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:44
S76	1	"5027253".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:44
S77	1	"20020167060".PN.	US-PGPUB	OR	ON	2005/09/25 08:46
S78	1	"20020167060".PN.	US-PGPUB	OR	ON	2005/09/25 08:49
S79	. 1	"6476463".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:50
S80	1	"6472598".PN.	USPAT; USOCR	OR	ON	2005/09/25 08:50
S81 ⁻	1	"5166772".PN.	USPAT; USOCR	OR.	ON	2005/09/25 08:51
S82	1	"4868639".PN	USPAT; USOCR	OR	ON	2005/09/25 08:51
S83	1	@ad<="20040329" and 'tape substrate' and 'chip' and ('balun' or 'short wave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 09:01
S84	37	@ad<="20040329" and 'tape' same 'substrate' and 'chip' and ('balun' or 'short wave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/25 09:01
S85	198	@ad<="20040329" and 'tape' and 'chip' and 'short wave'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/09/25 09:05
S86	83	@ad<="20040329" and 'tape' and 'chip' and 'balun'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:53
S87	12	@ad<="20040329" and 'tape' with 'substrate' and 'chip' and 'short wave'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2005/09/25 09:05
S88	746	@ad<="20040329" and (257/728). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19

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S89	1585	@ad<="20040329" and (257/724). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S90	300	@ad<="20040329" and (257/725). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S91	2128	@ad<="20040329" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/29 09:19
S94	87	@ad<="20040329" and 'tape' and 'chip' and 'baluns'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:27
S98	96	@ad<="20040329" and 'tape' same 'chip' with 'inductors'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:28
S99	8	@ad<="20040329" and 'tape' same 'chip' with 'couplers'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:28
S10 0	271	@ad<="20040329" and 'tape' same ('chip' or 'IC') with ('filters' or 'inductors' or 'baluns' or 'shortwave')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:30
S10 1	35	@ad<="20040329" and 'tape' same ('chip' or 'IC') with ('filters' or 'inductors' or 'baluns' or 'shortwave') and encapsul\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:35
S10 3	255	@ad<="20040329" and 'package' same 'IC' same 'transmission line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:37
S10 4	36	@ad<="20040329" and 'package' same 'IC' same 'transmission line' and encapsul\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:44
S10 .5	46	@ad<="20040329" and packag\$4 same 'high frequency' same ('element' or 'components') same encapsul\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:56

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S10 6	1	"5382829".PN.	USPAT; USOCR	OR	ON	2005/12/19 15:49
S10 7	1	"5128744".PN.	USPAT; USOCR	OR	ON	2005/12/19 15:49
S10 8	1	"4956695".PN.	USPAT; USOCR	OR	ON	2005/12/19 15:49
S10 9	1	"4550357":PN.	USPAT; USOCR	OR	ON	2005/12/19 15:50
S11 0	114	encapsul\$5 and S88	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:54
S11 1	409	encapsul\$5 and S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:54
S11 2	91	encapsul\$5 and S90	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:55
S11 3	673	encapsul\$5 and S91	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:55
S11 4	9	@ad<="20040329" and packag\$4 same 'RF device' same encapsul\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:57
S11 5	93	@ad<="20040329" and packag\$4 same 'RF' same 'device' same encapsul\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:57
S11 6	20	@ad<="20040329" and 'tape' with packag\$4 and 'IC' and 'coupler' and 'filter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/19 15:59
S11 7	1	"6218729".PN.	USPAT; USOCR	OR	ON	2005/12/19 16:04
S11 8	1	"6169329".PN.	USPAT; USOCR	OR	ON	2005/12/19 16:04
S11 9	687	@ad<="20040329" and (361/728). ccls.	US-PGPUB; USPÄT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19

S12 0	189	@ad<="20040329" and (257/748). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:18
S12 1	696	@ad<="20040329" and (361/728). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:05
S12 2	1301	@ad<="20040329" and (257/734). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S12 3	766	@ad<="20040329" and (257/728). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S12 4	310	@ad<="20040329" and (257/725). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S12 5	1623	@ad<="20040329" and (257/724). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S12 6	2187	@ad<="20040329" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/29 09:19
S12 7	37	("20010008305" "20020011654" "20020024122" "20020140061" "20020140068" "2596993" "3435815" "3734660" "3838984" "4054238" "4189342" "4258381" "4289922" "4301464" "4332537" "4417266" "4451224" "4530152" "4646710" "4707724" "4737839" "4756080" "5168368" "5365106" "5592019" "6113473" "6215179" "6247229" "6295977" "6307272" "6369454" "6482680" "6507120" "RE36613" "RE36907").PN. OR ("6833609").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/19 08:57
S12 8	1	"5969947".PN.	USPAT; USOCR	OR	ON	2006/09/19 08:58
S12 9	1	"5849608".PN.	USPAT; USOCR	OR	ON.	2006/09/19 08:58

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S13 0	1229	@ad<="20040329" and (257/668). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON .	2006/09/19 09:04
S13 1	699	@ad<="20040329" and (361/728). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:05
S13 3	26	@ad<="20040329" and "tape substrate" same encapsulat\$3 same (chip or "IC")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:18
S13 4	57	@ad<="20040329" and "flexible substrate" same encapsulant same (chip or "IC")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/09/19 09:18
S13 5	17	@ad<="20040329" and tape and (chip or "IC" or die) and coupler and balun and filter and inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:35
S13 7	985	@ad<="20040329" and tape and (chip or "IC" or die) same "transmission line"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:37
S13 8	. 0	@ad<="20040329" and tape and (chip or "IC" or die) and (coupler same balun same filter same inductor same "transmission line")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:36
S13 9	4	@ad<="20040329" and tape and (chip or "IC" or die) and coupler same balun same filter same inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:36
S14 0	49	@ad<="20040329" and tape and (chip or "IC" or die) and "transmission line" and encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:37
S14 1	18	@ad<="20040329" and tape with package and chip and coupler and filter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 09:40
S14 2	103	@ad<="20040329" and tape and chip and balun	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/09/19 09:54

S14 3	17	@ad<="20040329" and tape and chip and balun and encapsul\$4	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2006/09/19 09:54
S14	2	("6437984").PN.	DERWENT; IBM_TDB US-PGPUB;	OR	OFF	2006/09/19 10:25
4		(0437904).PN.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OK .	OFF	2000/09/19 10:20
S14 5	28	@ad<="20040329" and tape with package and (chip or "IC" or die) and coupler and filter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/26 08:16
S14 6	2	@ad<="20040329" and "OCCHIPINTI JOSEPH"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/26 08:17
S14 7	16	"coccioli" and antenna	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/26 08:53
S14 8	21	("20010016251" "20020027531" "20020050635" "20020079568" "20020125546" "20020159242" "20020167084" "20030030985" "5640048" "5757074" "6114962" "6236366" "6246327" "6265977" "6353540" "6388623" "6396135" "6421013" "6534711" "6582979"). PN. OR ("6818985").URPN.	US-PGPUB; USPAT; USOCR	OR .	ON	2006/12/26 08:19
S14 9	64	("4417413" "4483067" "4583099" "4719140" "5026452" "5250341" "5404581" "5430441" "5463404" "5541399" "5574470" "5598032" "5690773" "5751256" "5847931" "5880934" "5892661" "5903239" "5909050" "5936305" "5994166" "6018299" "6049461" "6088901" "6100804" "6161761" "6181278" "6219238" "6232667").PN. OR ("6421013").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/26 08:45
S15 0	9	"coccioli roberto"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/12/26 09:02

S15 1	2	("6421013").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	OFF	2006/12/26 09:03
			IBM_TDB		,	

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